

**Amendments to the Claims**

This listing of claims will replace all prior listings of claims in the application.

**Listing of Claims**

1.-19. (Canceled)

20. (Previously Presented) The plated resin molded article according to claim 31, wherein the maximum value of the adhesive strength, according to JIS H8630, between the thermoplastic resin molded article and the metal plating layer is at least 10 kPa.

21. (Previously Presented) The plated resin molded article according to claim 31, applied as an automotive component.

22. (Withdrawn) A method of producing a plated resin molded article according to claim 30, wherein the plated resin molded article is produced by plating metal on the surface of the thermoplastic resin molded article, the method comprising the step of contact-treating the thermoplastic resin molded article with an acid or base that does not contain a heavy metal, as a treatment preceding a metal plating step, and wherein a step of etching with a heavy metal-containing acid is not included.

23. (Withdrawn) The method of producing a plated resin molded article according to claim 22, comprising the steps of: removing fat of the thermoplastic resin molded article; contact-treating the thermoplastic resin molded article with an acid or base that does not contain heavy metal; and a plating step, wherein the method does not include a step of etching with a heavy metal-containing acid.

24. (Withdrawn) The method of producing a plated resin molded article according to claim 22, comprising the steps of: removing fat of the plastic resin molded article; contact-treating the thermoplastic resin molded article with an acid or base that does not contain a heavy metal; treating the thermoplastic resin molded article with a catalyst-imparting liquid; and a plating step, wherein the method does not include a step of etching with a heavy metal-containing acid.

25. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the concentration of the acid or base used in the step of contact-treating with an acid or base that does not contain a heavy metal is less than 4 normal.

26. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the step of contact-treating with an acid or base that does not contain a heavy metal is a step of immersing the thermoplastic resin molded article in acid or base that does not contain heavy metal.

27. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the step of contact treating with an acid or base that does not contain a heavy metal is a step of immersing the thermoplastic resin molded article for 20 to 0.5 minutes at a liquid temperature of 10 to 80°C in an acid or base that does not contain a heavy metal.

28. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the acid that does not contain a heavy metal is selected from hydrochloric acid, phosphoric acid, sulfuric acid and organic acids.

29. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the base that does not contain a heavy metal is selected from hydroxides of an alkali metal or alkali earth metal.

30. (Canceled)

31. (Currently Amended) A plated resin molded article that has a metal plating layer provided on the surface of a thermoplastic resin article formed from a composition comprising the following components:

(A) 10 to 90 mass % of a matrix resin that has a water absorption after 24 hours in 23°C water, according to ISO62, of at least 0.6% and selected from the group consisting of a polyamide 6 resin, a polyamide 66 resin and a polyamide 6/66 resin;

(B) 90 to 10 mass % of a polyphenylene ether-based resin;

(C) a water-soluble substance having a solubility at 25°C of not more than 300g in 100g of water and selected from the group consisting of pentaerythritol and dipentaerythritol in an amount of 0.01 to 50 mass parts per 100 mass parts of the sum of components (A) and (B);

(D) ~~at least one of a surfactant and a coagulant~~ in an amount of 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B), the surfactant being an  $\alpha$ -olefin sulfonate; and

(E) a phosphorus compound comprising one or more members selected from the group consisting of a condensed phosphate ester, an aliphatic acid aromatic phosphate ester of an orthophosphate ester, an alkali metal salt of melamine polyphosphate tripolyphosphoric acid, pyrophosphoric acid, orthophosphoric acid or hexametaphosphoric acid and phytic acid, an alkali metal salt thereof and an alkanolamine salt thereof in an amount of 0.1 to 30 mass parts per 100 mass parts of the sum of components (A) and (B).

32. (Previously Presented) The plated resin molded article according to claim 31, wherein the water-soluble substance (C) is present in an amount of from 0.01 to 15 mass parts per 100 mass parts of the sum of components (A) and (B).

33. (Previously Presented) The plated resin molded article according to Claim 31, wherein the water-soluble substance (C) is present in an amount of from 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B) and a surfactant (D) is present in an amount of from 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B).

34. (Previously Presented) The plated resin molded article according to Claim 33, additionally comprising a phosphorus compound (E) in an amount of 0.1 to 10 mass parts per 100 mass parts of the sum of components (A)+(B).

35. (Previously Presented) The plated resin molded article according to Claim 32, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether) and component (C) is dipentaerythritol.

36. (Previously Presented) The plated resin molded article according to Claim 33, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether), component (C) is dipentaerythritol and component (D) is an  $\alpha$ -olefin sulfonate.

37. (Previously Presented) The plated resin molded article according to Claim 34, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether), component (C) is dipentaerythritol, component (D) is an  $\alpha$ -olefin sulfonate and component (E) is triphenyl phosphate.

38. (Previously Presented) The plated resin molded article according to claim 31, wherein the condensed phosphate esters are selected from the group consisting of triphenyl phosphate, tricresyl phosphate, trixylenyl phosphate, tris(isopropylphenyl) phosphate, tris(o- or p-phenylphenyl) phosphate, trinaphthyl phosphate, cresyl diphenyl phosphate, xylenyl diphenyl phosphate, di(isopropylphenyl) phenyl phosphate, o-phenylphenyl dicresyl phosphate, tris(2,6-dimethylphenyl) phosphate, tetraphenyl m-phenylene diphosphate, tetraphenyl p-phenylene diphosphate, phenyl resorcinol polyphosphate, bisphenol A-bis(diphenyl phosphate), bisphenol A-polyphenyl phosphate and dipyrocatechol hypodiphosphate.

39. (Previously Presented) The plated resin molded article according to claim 31, wherein the aliphatic acid-aromatic phosphate ester of an orthophosphate ester is selected from the group consisting of diphenyl (2-ethylhexyl) phosphate, diphenyl 2-acryloyloxyethyl phosphate, diphenyl 2-methacryloyloxyethyl phosphate, diphenyl neopentyl phosphate, pentaerythritol diphenyl diphosphate and ethyl pyrocatechol phosphate.

40. (Previously Presented) The plated resin molded article according to claim 31, wherein the condensed phosphate esters are triphenyl phosphate.

41.-49. (Canceled)

50. (Previously Presented) The plated resin molded article according to claim 31, wherein (E) the condensed phosphate ester is triphenyl phosphate and (A) the matrix resin is a polyamide resin.